



## Message from the Editor

Here, we offer the fifth volume of Transactions of The Japan Institute of Electronics Packaging (Trans. JIEP). I believe that Trans. JIEP is firmly established as an important technical journal in microelectronics packaging technologies. I would like to make a most cordial acknowledgment to all the persons involved in publishing Trans. JIEP, including authors, reviewers/referees, editorial committee members, society members, and the secretariat. This year's volume contains excellent and interesting papers in the field of 3-D packaging (wafer level and TSV), reliability (mechanical stress/strain analysis and interfacial adhesion characteristics), printed electronics, novel coreless substrates, thermal management (cooling and heat dissipation), high-frequency signal transmission including test methods, new materials (wiring materials and heat sinks), material engineering (new surface treatment process), and so on. I think that there is no doubt that these papers will yield valuable information to you.

I know that there are many superior papers which have been presented in some JIEP Conferences/Symposiums, technical meetings, and so on. I also know that there are many other achievements which have not been submitted elsewhere. I hope that you will publish your important and remarkable achievements through Trans. JIEP.

This year, to inform you the current status of electronics packaging technologies and industries in Asia, the JIEP started a new activity in the ICEP\*; the special session titled IAAC\*\* (so this year's conference is specially called ICEP-IAAC 2012). The background to this session is explained in this volume.

December 25, 2012

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Editor-in-Chief  
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Meisei University

\*ICEP: International Conference on Electronics Packaging

\*\*IAAC: IMAPS All Asia Conference

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■Preface – Message from the Editor / Kaoru HASHIMOTO

■Technical Papers

Use of Modified Accumulated Damage Model to Predict Fatigue Failure Lives of Sn-Ag-Cu-based Solder Joints in Ball-Grid-Array-Type Packages / Takeshi TERASAKI, Hisashi TANIE, Nobuhiko CHIWATA, Motoki WAKANO, and Masaru FUJIYOSHI	1
Adhesion Characteristics of Magnetron-Sputter-Deposited Copper on Smooth Cycloolefin for Realizing Wiring with High-Frequency Signal Propagation / Tetsuya GOTO, Takatoshi MATSUO, Masamichi IWAKI, Kazuki SOEDA, Ryosuke HIRATSUKA, Shigetoshi SUGAWA, and Tadahiro OHMI	12
Development of Copper Materials and Processing for Printed Electronics / Kyoko KURODA, Hideo NAKAKO, Maki INADA, Takaaki NOUDOU, and Yasushi KUMASHIRO	20
Electrical Test Method for Interconnect Open Defects in 3D ICs / Tomoaki KONISHI, Hiroyuki YOTSUYANAGI, and Masaki HASHIZUME	26
Fabrication and Characterization of Ferroelectric PZT and BaTiO <sub>3</sub> Thin Films on Releasable Electrode Structures / Erika KOMINE, Motoyuki OZAKI, Tadatomo SUGA, Masaaki ICHIKI, and Toshihiro ITOH	34
Quantitative Adhesion Properties and Interfacial Behavior of SiCN Barrier Layer and Cu Film / Satoko ABE, Teruhisa BABA, Kenichi UEOKA, Yohei TAKAHASHI, Kouji YONEDA, and Jiping YE	41
Surface Modification of Polyethylene Terephthalate (PET) by 172-nm Excimer Lamp / Takashi KASAHARA, Shuichi SHOJI, and Jun MIZUNO	47
Low Warpage Coreless Substrate for IC Packages / Mamoru KURASHINA, Daisuke MIZUTANI, Masateru KOIDE, Manabu WATANABE, Kenji FUKUZONO, Nobutaka ITOH, and Hitoshi SUZUKI	55
Use Isothermal Surface to Help Understanding the Spatial Representation of Structure Function / Yafei LUO	63
Development of Functional Porous Heat Sink for Cooling High-Power Electronic Devices / Kazuhisa YUKI and Koichi SUZUKI	69
Thermal Performance of 3D IC Package with Embedded TSVs / Ra-Min TAIN, Ming-Ji DAI, Yu-Lin CHAO, Sheng-Liang LI, Heng-Chieh CHIEN, Sheng-Tsai WU, Wei LI, and Wei-Chung LO	75
Wafer Level Packaging to Address Future Direct Chip Attach Needs / Yoshihiro TOMITA, Yoko SEKIHARA, Jiro KUBOTA, Kinya ICHIKAWA, and Bob SANKMAN	85
Homogenizing and Applying Dielectric Film to Wafer-Level Film Preparation / Kazutaka SUESHIGE, Keita IIMURA, Masaaki ICHIKI, Tadatomo SUGA, and Toshihiro ITOH	92
Development of High Productive Micro Solder Flip Chip Bonding Process / Daisuke SAKURAI, Takatoshi OSUMI, Kazuya USHIROKAWA, Takashi NAKAMURA, and Takatoshi ISHIKAWA	99
FEM Analysis on Mechanical Stress of 2.5D Package Interposers / Takashi HISADA, Toyohiro AOKI, Junko ASAI, and Yasuharu YAMADA	107
Structure and Process for High Inductance by Suppressing Magnetic Flux Path between Internal Conductors in Multilayer Ferrite Ceramic Inductor / Minami TAKATO, Ken SAITO, and Fumio UCHIKOBA	115
Over Molding Process Development for a Stacked Wafer-level Chip Scale Package with Through Silicon Vias (TSVs) / Yoshimi TAKAHASHI, Rajiv DUNNE, Masazumi AMAGAI, Yohei KOTO, Shoichi IRIGUCHI, Tom BONIFIELD, Philipp STEINMANN, and David C. STEPNIAK	122
■Information Message to the First All Asia Jisso Conference (ICEP-IAAC2012) / Fumio MIYASHIRO	132